



**New pluggable  
STM-1e SFP module  
reduces development costs  
for SDH Network OEM vendors  
and improves end user flexibility**

TDK Semiconductor, a leader in mixed-signal ICs for DS3/E3 and STM1e/E4 coaxial interfaces, has added a pluggable SFP module option to its family of WAN Line Interface Units (LIUs). By emulating the interface of an optical OC-3/STM1 transceiver module, the STM-1e SFP allows system OEM vendors to offer greater flexibility without additional hardware development.

As bandwidth requirements increase, service providers can minimize additional costs by upgrading existing legacy coaxial infrastructure from 34/45Mbps (E3/DS3) to 155Mbps (STS-3/STM-1).

**Features:**

- MSA compatible Small Form-factor Pluggable (SFP) module for STM-1 electrical (STM-1e) interfaces
- Host interface compatible with existing OC-3/STM-1 line cards using the SFP form factor
- Loss of Signal detection and Tx Disable capabilities
- Low power dissipation (600mW typ)
- Extended Temperature (-10C to 85C) operation
- Exceeds all ITU-T and Telcordia requirements for Receiver Jitter Tolerance and Intrinsic Transmit Jitter (0.05 UIpp typ)
- 75ohm DIN 1.0/2.3 coax network interface

Ordering Number	Description
<b>STM1E-SFP/EVK</b>	STM-1e SFP Eval Kit *Includes 1.0/2.3 to BNC cable assemblies and test board